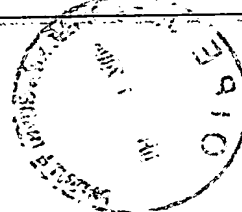


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(54) SILICA COATING FILM AND SEMICONDUCTOR UNIT WITH THE SILICA COATING FILM

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a silica coating film excellent in adhesiveness (especially in adhesiveness in CMP process) and a high quality semiconductor unit little in signal delay and high in reliability.

SOLUTION: This silica coating film is prepared by coating a composition containing a polysiloxane having an integration ratio of 0.01-0.3 of a proton of H-Si bond and a proton of R-Si bond (wherein R is a 1-18C alkyl group or a 1-18C aryl group) measured by ¹H-NMR spectrometry and an organic solvent, and drying, and in this semiconductor unit the silica coating film is used as an interlayer insulating film for multilayer wiring.

LEGAL STATUS

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